

# FM220-S THRU FM2200-S

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# FM220-S THRU FM2200-S

## 2.0A Surface Mount Schottky Barrier Rectifiers - 20-200V

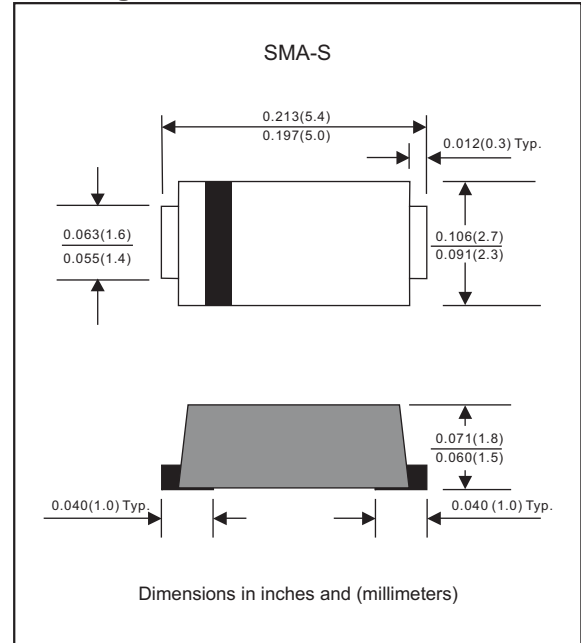
### Features

- Batch process design, excellent power dissipation offers better reverse leakage current and thermal resistance.
- Low power loss, high efficiency.
- High current capability, low forward voltage drop.
- High surge capability.
- Guardring for overvoltage protection.
- Ultra high-speed switching.
- Silicon epitaxial planar chip, metal silicon junction.
- Lead-free parts meet environmental standards of MIL-STD-19500 /228
- Suffix "-H" indicates Halogen free parts, ex. FM220-S-H.

### Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, DO-214AC / SMA-S
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any
- Weight : Approximated 0.05 gram

### Package outline



### Maximum ratings and Electrical Characteristics (AT T<sub>A</sub>=25°C unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.1	I <sub>O</sub>			2.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC methode)	I <sub>FSM</sub>			50	A
Reverse current	V <sub>R</sub> = V <sub>RRM</sub> T <sub>J</sub> = 25°C	I <sub>R</sub>			0.5	mA
	V <sub>R</sub> = V <sub>RRM</sub> T <sub>J</sub> = 100°C				10	
Thermal resistance	Junction to ambient	R <sub>θJA</sub>		64		°C/W
	Junction to case	R <sub>θJC</sub>		32		°C/W
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	C <sub>J</sub>		160		pF
Storage temperature		T <sub>STG</sub>	-65		+175	°C

SYMBOLS	V <sub>RRM</sub> <sup>*1</sup> (V)	V <sub>RMS</sub> <sup>*2</sup> (V)	V <sub>R</sub> <sup>*3</sup> (V)	V <sub>F</sub> <sup>*4</sup> (V)	Operating temperature T <sub>J</sub> , (°C)
FM220-S	20	14	20	0.50	-55 to +125
FM230-S	30	21	30		
FM240-S	40	28	40		
FM245-S	45	31.5	45		
FM250-S	50	35	50	0.70	-55 to +150
FM260-S	60	42	60		
FM280-S	80	56	80	0.85	
FM2100-S	100	70	100		
FM2150-S	150	105	150	0.90	
FM2200-S	200	140	200	0.92	

\*1 Repetitive Peak Reverse Voltage

\*2 RMS Voltage

\*3 Continuous Reverse Voltage

\*4 Maximum Forward Voltage @I<sub>F</sub>=2.0A

## Rating and characteristic curves (FM220-S THRU FM2200-S)

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

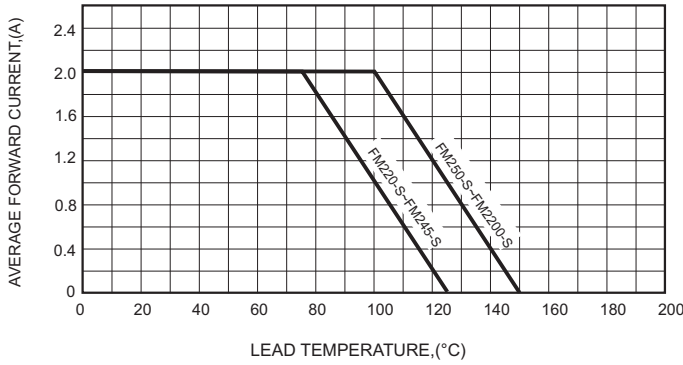


FIG.2-TYPICAL FORWARD CHARACTERISTICS

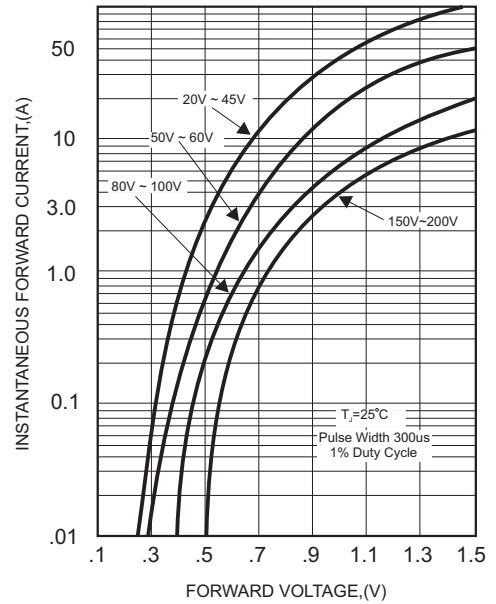


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

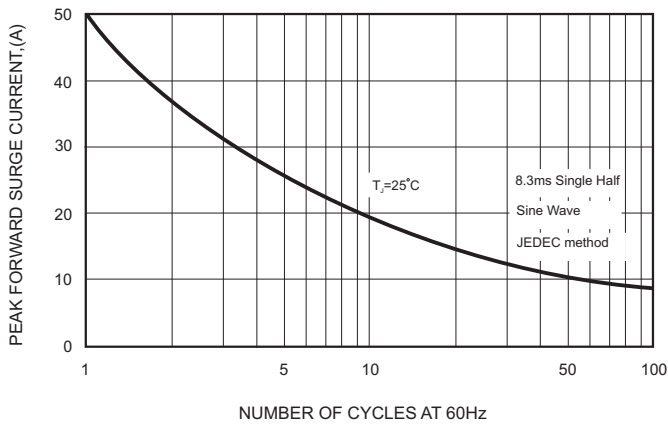


FIG.5 - TYPICAL REVERSE CHARACTERISTICS

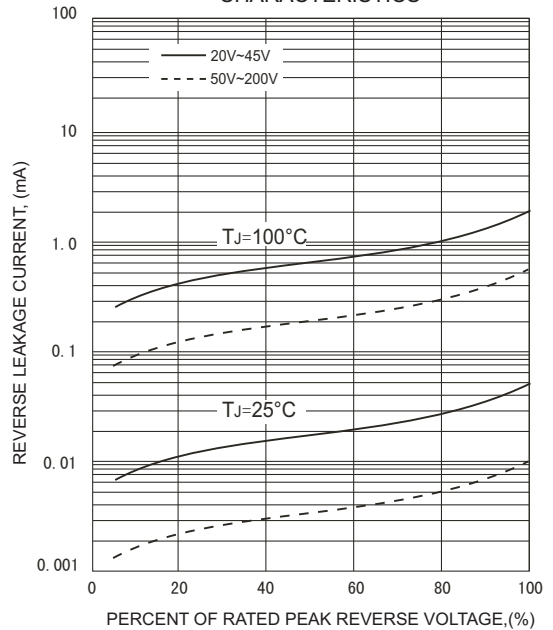
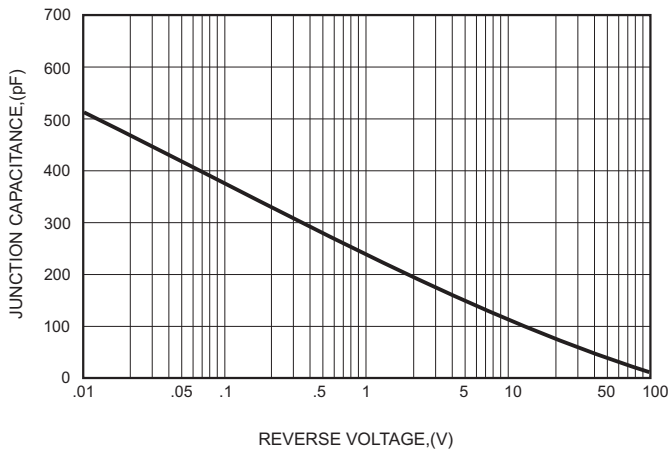




FIG.4-TYPICAL JUNCTION CAPACITANCE



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## Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

## Marking

Type number	Marking code
FM220-S	SK22
FM230-S	SK23
FM240-S	SK24
FM245-S	SK24
FM250-S	SK25
FM260-S	SK26
FM280-S	SK28
FM2100-S	S210
FM2150-S	S215
FM2200-S	S220

## Suggested solder pad layout

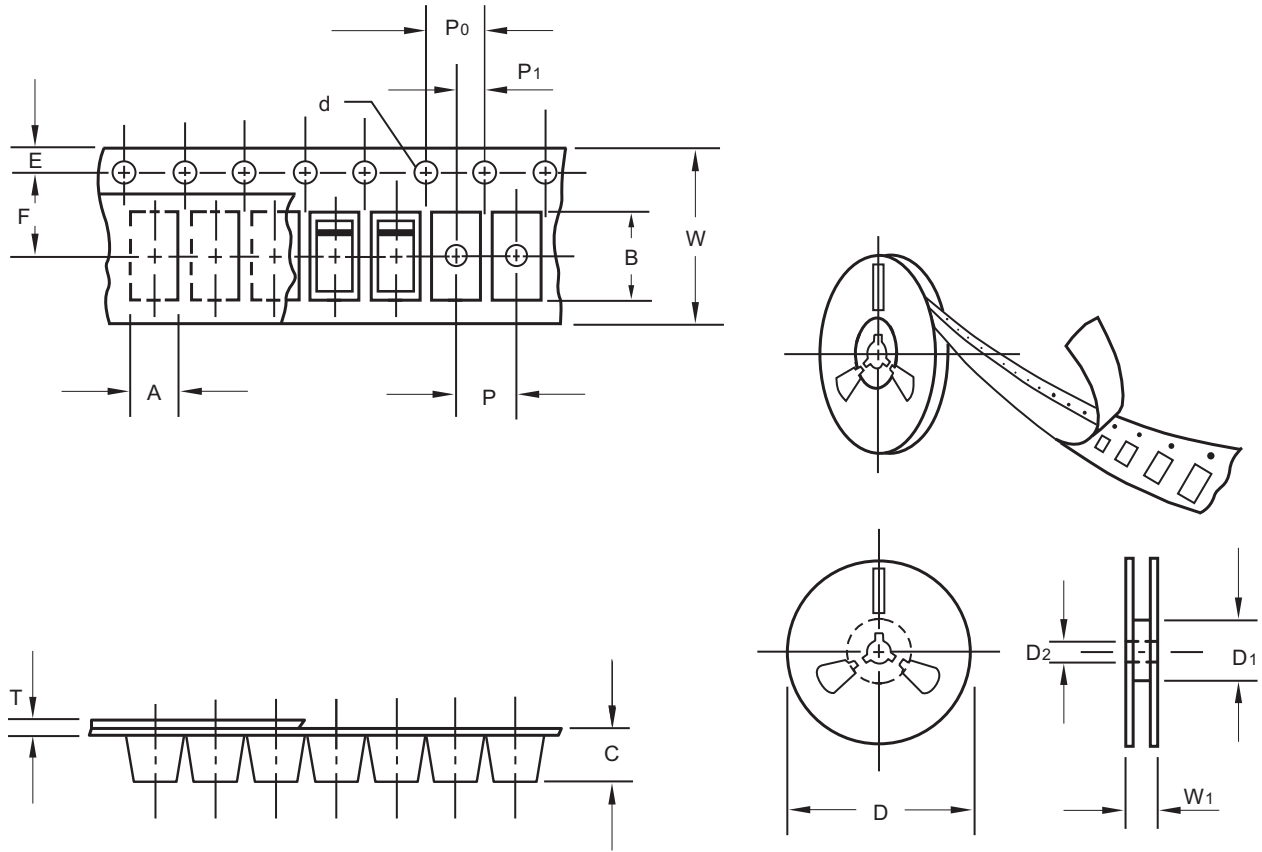


Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMA-S	0.063 (1.60)	0.059 (1.50)	0.110 (2.80)

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## Packing information



unit:mm

Item	Symbol	Tolerance	SMA-S
Carrier width	A	0.1	2.90
Carrier length	B	0.1	5.50
Carrier depth	C	0.1	2.10
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D1	min	50.00
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	62.00
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	12.00
Reel width	W1	1.0	18.00

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

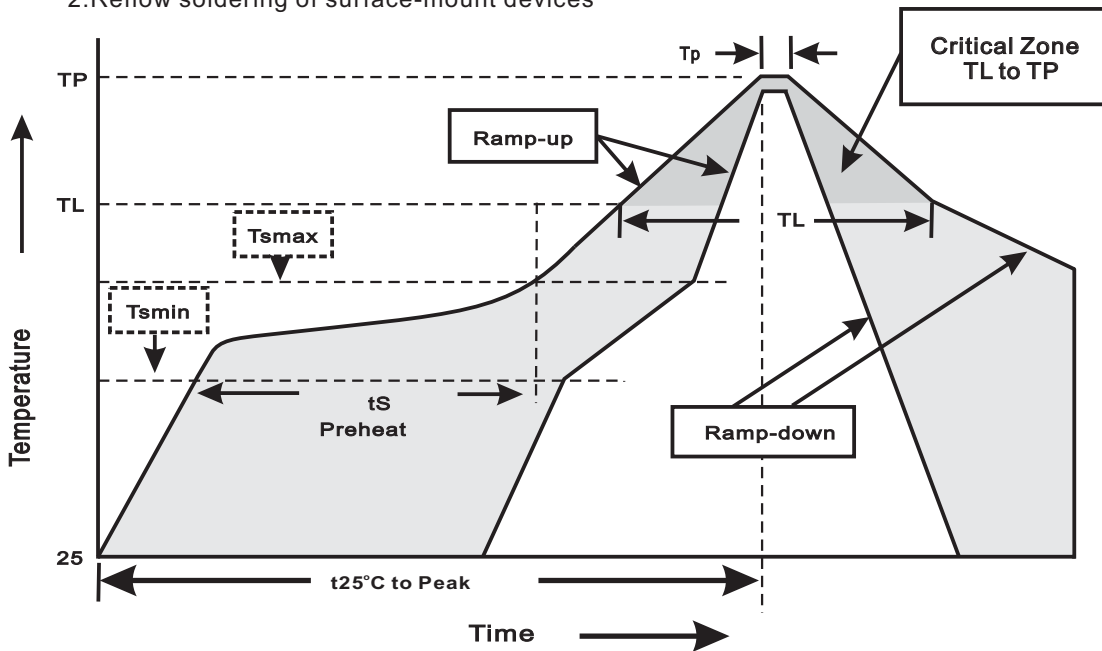
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## Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMA-S	7"	2,000	4.0	20,000	183*155*183	178	382*356*392	160,000	15.5
	13"	7,500	4.0	15,000	337*337*37	330	350*330*360	120,000	14.2

## Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



### 3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T <sub>L</sub> to T <sub>P</sub> )	<3°C/sec
Preheat -Temperature Min(T <sub>smin</sub> ) -Temperature Max(T <sub>smax</sub> ) -Time(min to max)(t <sub>s</sub> )	150°C 200°C 60~120sec
T <sub>smax</sub> to T <sub>L</sub> -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T <sub>L</sub> ) -Time(t <sub>L</sub> )	217°C 60~260sec
Peak Temperature(T <sub>P</sub> )	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t <sub>P</sub> )	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

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## High reliability test capabilities

Item Test	Conditions	Reference
1. Solder Resistance	at 260±5°C for 10±2sec. immerse body into solder 1/16"±1/32"	MIL-STD-750D METHOD-2031
2. Solderability	at 245±5°C for 5 sec.	MIL-STD-202F METHOD-208
3. High Temperature Reverse Bias	V <sub>R</sub> =80% rate at T <sub>J</sub> =125°C for 168 hrs.	MIL-STD-750D METHOD-1038
4. Forward Operation Life	Rated average rectifier current at T <sub>A</sub> =25°C for 500hrs.	MIL-STD-750D METHOD-1027
5. Intermittent Operation Life	T <sub>A</sub> = 25°C, I <sub>F</sub> = I <sub>O</sub> On state: power on for 5 min. off state: power off for 5 min. on and off for 500 cycles.	MIL-STD-750D METHOD-1036
6. Pressure Cooker	15P <sub>SIG</sub> at T <sub>A</sub> =121°C for 4 hrs.	JESD22-A102
7. Temperature Cycling	-55°C to +125°C dwelled for 30 min. and transferred for 5min. total 10 cycles.	MIL-STD-750D METHOD-1051
8. Forward Surge	8.3ms single half sine-wave , one surge.	MIL-STD-750D METHOD-4066-2
9. Humidity	at T <sub>A</sub> =85°C, RH=85% for 1000hrs.	MIL-STD-750D METHOD-1021
10. High Temperature Storage Life	at 175°C for 1000 hrs.	MIL-STD-750D METHOD-1031